# Wire Bondable Resistor/Capacitor Circuits



#### **WBC-RC Series**

- · Integrated resistor and capacitor
- Proven IRC TaNSil® technology
- 3 types AC Terminator, Tapped and T-Filter



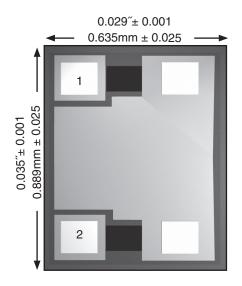
#### **Electrical Data**

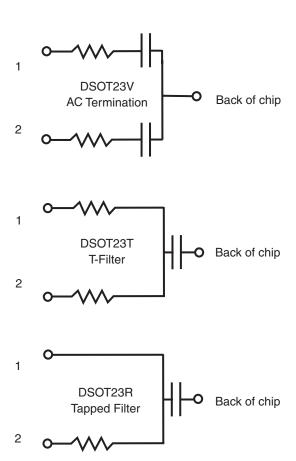
		AC Termination	T-Filter	Tapped Filter	
Resistance Value		47Ω	100Ω	33Ω	
Capacitance Value		47pF	80pF	47pF	
Absolute Tolerance	Resistance	±10%			
	Capacitance	±20%			
Absolute TCR	Resistance	±150ppm/°C			
	Capacitance	±200ppm/°C			
Package Power Rating		250mW			
Resistor Element Power Rating		125mW			
Capacitor Breakdown Voltage		25V			
Operating Temperature		-55°C to +125°C			
Resistor Noise		<-25dB			
Substrate Material		Silicon			
Substrate Thickness		0.010″ ±0.001 (0.254mm ±0.025)			
Bond Pad Metallization		Aluminum: 10KÅ minimum			
Backside		3KÅ Gold minimum			
Passivation		Silicon Dioxide or Silicon Nitride			

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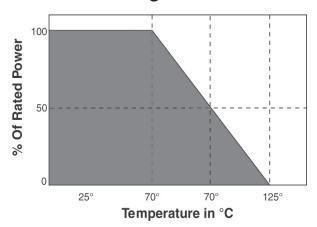


### Physical and Schematic Data





### **Power Derating Data**



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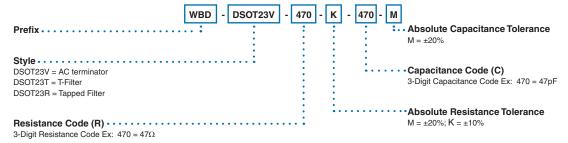
### Environmental Data (Resistor)

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

### **Environmental Data (Capacitor)**

Test	Method	Мах ∆С
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.25% + 0.25pF max
Moisture Resistance	MIL-STD-202 Method 106	±1.0% + 0.25pF max
Short Time Overload	+25°C, 5 seconds 1.5 X rated voltage	±0.25% + 0.25pF max
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.25% + 0.25pF max
High Temperature Exposure	100 hours @ 150°C ambient	±0.25% + 0.25pF max

### **Ordering Data**



#### **Packaging**

Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.